

**FEATURES**

- Microminiature package.
- Standard recovery.
- Stable surface films integrally bonded to the device crystal.
- Meet or exceed requirements of MIL-S-19500.

**MAXIMUM RATINGS**

Operating Temperature:  $-65^{\circ}\text{C}$  to  $+175^{\circ}\text{C}$ .  
Storage Temperature:  $175^{\circ}\text{C}$ .  
Power Dissipation: 100 mW @  $25^{\circ}\text{C}$  Au plated kovar leads

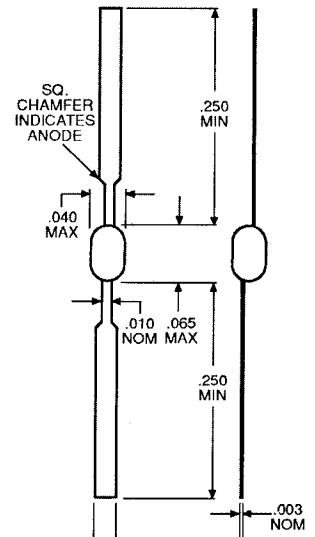
**ELECTRICAL CHARACTERISTICS**

TYPE	BREAKDOWN VOLTAGE (MIN.) @ 100 $\mu\text{A}$ $V_{(BR)}$	FORWARD CURRENT (MIN.) @ 1.0 V $I_F$	REVERSE CURRENT (MAX.) $I_R$ @ $V_R$		TEST VOLTAGE $V_R$	AVERAGE RECTIFIED CURRENT $I_o$
			$\mu\text{A}$			
			25 $^{\circ}\text{C}$	150 $^{\circ}\text{C}$		
	VOLTS	mA			VOLTS	mA
MC456A	30	100	0.025	5.0	-25V	150
MC457A	70	100	0.025	5.0	-60V	150
MC458A	150	100	0.025	5.0	-125V	150
MC459A	200	100	0.025	5.0	-175V	150
MC461A	30	100	0.5	30.0	-25V	150
MC462A	70	100	0.5	30.0	-60V	150
MC463A	200	100	0.5	30.0	-175V	150
MC464A	150	100	0.5	30.0	-125V	150
MC482B	40	100	0.025	5.0	-30V	150
MC483B	80	100	0.025	5.0	-60V	150
MC484B	150	100	0.025	5.0	-125V	150
MC485B	200	100	0.025	5.0	-175V	150
MC486B	250	100	0.025	5.0	-225V	150

**NOTES:**

- Power Dissipation: 300 mw @  $25^{\circ}\text{C}$ .
- Operating Temperature Range: @  $-65^{\circ}\text{C}$  to  $+175^{\circ}\text{C}$ .
- Storage Temperature:  $-65^{\circ}\text{C}$  to  $+175^{\circ}\text{C}$

**PELLET DIODES**



**FIGURE 1**  
Package H

**MECHANICAL CHARACTERISTICS**

CASE: Ultra stable epoxy encapsulation.

LEAD MATERIAL: Gold plated kovar or gold plated silver.

MARKING: EIA color code bands.

POLARITY: Color bands on cathode leads.